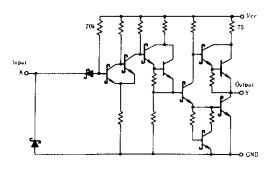
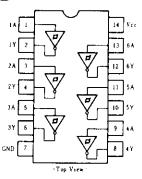
## **■**CIRCUIT SCHEMATIC(1/6)



#### **■PIN ARRANGEMENT**



# **ELECTRICAL CHARACTERISTICS** ( $Ta = -20 \sim +75^{\circ}C$ )

Item	Symbol	Test Conditions		min	typ*	max	Unit
	$V_T$	$V_{CC} = 5V$		1.4	1.6	1.9	V
Input threshold voltage	Vr.	$V_{CC} = 5V$		0.5	0.7	1.0	V
Hysteresis	Vr+- Vr-	$V_{CC} = 5V$		0.4	0.9	-	v
Output voltage	Voн	$V_{CC} = 4.75 \text{V}, V_I = 0.5 \text{V}, I_{OH} = -400 \mu\text{A}$		2.7	-	-	V
	Vol	$V_{CC} = 4.75 \text{V},  V_I = 1.9 \text{V}$	Io L = 8mA	-		0.50	v
			IoL = 4mA	_		0.40	
Input threshold current	Ir+	$V_{CC} = 5V$ , $V_I = V_T^+$			-0.14	_	m A
	Ir '	$V_{CC} = 5V$ , $V_I = V_T$			-0.18	_	mА
Input current	Iн	$V_{CC} = 5.25 \text{V},  V_l = 2.7 \text{V}$		_	- 1	20	μA
	ItL	$V_{CC} = 5.25 \text{V},  V_I = 0.4 \text{V}$		_	- !	-0.4	mА
	I <sub>I</sub>	$V_{CC}=5.25V,  V_I=7V$		_	- 1	0.1	m A
Short-circuit output current	los	<i>Vcc</i> = 5.25V		20	-	-100	mА
Supply current	Іссн	$V_{CC} = 5.25 \text{V}$		_	8.6	16	mA
	<b>I</b> cci.	$V_{CC} = 5.25 \text{V}$		_	12	21	mΑ
Input clamp voltage	Vik	$V_{CC} = 4.75 \text{V},  I_{IN} = -18 \text{mA}$		_	- 1	1.5	v

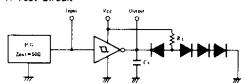
<sup>\*</sup> VCC=5V, Ta=25°C

# **ESWITCHING CHARACTERISTICS** ( $V_{cc}=5V$ , $T_a=25^{\circ}C$ )

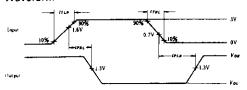
Item	Symbol	Test Conditions	min	typ	max	Unit
Propagation delay time	tplh	$C_L = 15 \mathrm{pF},  R_L = 2 \mathrm{k} \ \Omega$	-	15	22	ns
	<i>tphl</i>			15	22	ns

#### TESTING METHOD

1. Test Circuit



#### Waveform



Notes) 1. Input pulse;  $t_{TLH} \leq 15$ ns,  $t_{THL} \leq 6$ ns, PRR = 1MHz, duty cycle=50%

- C<sub>L</sub> includes probe and jig capacitance.
   All diodes are 1\$2074 (D).

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

Unit: mm

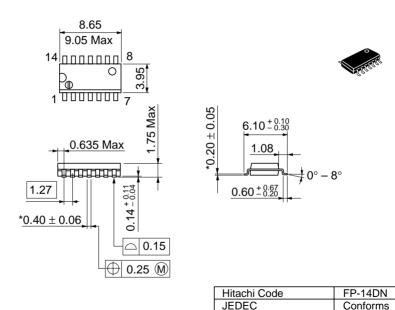


Weight (reference value)

0.23 g

\*Dimension including the plating thickness
Base material dimension

Unit: mm



EIAJ

Weight (reference value)

Conforms

0.13 g

\*Pd plating

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